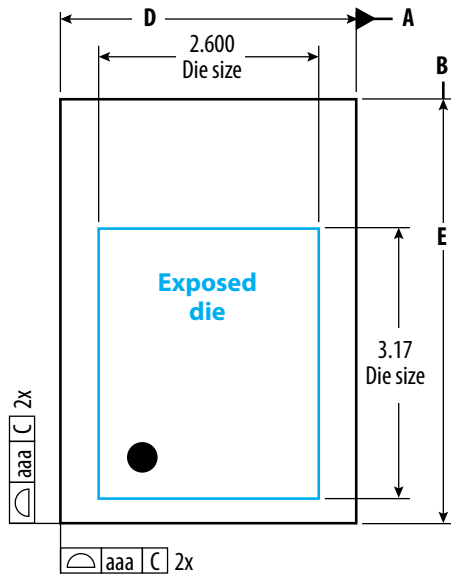
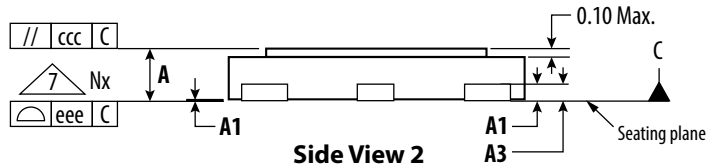
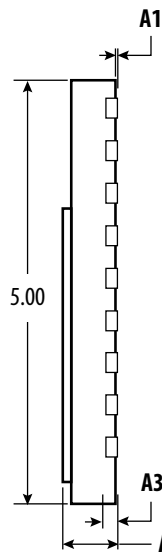


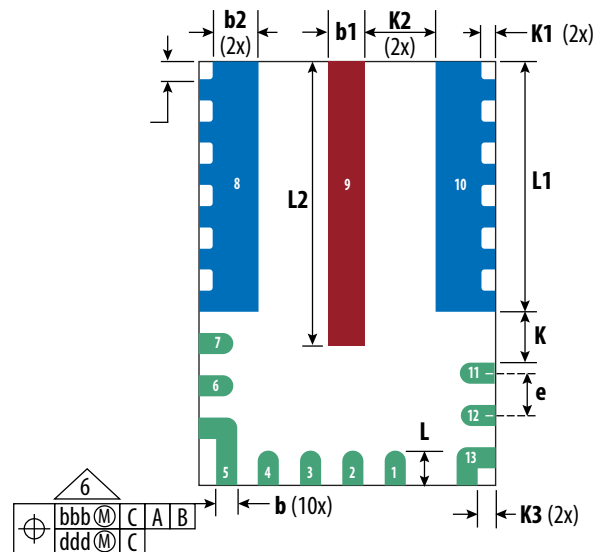
Pads 1-7, 11, 12 and 13 are IC pins;  
 Pad 9 is a SW pin;  
 Pad 8 is a PGND pin and 10 is a  $V_{IN}$  pin



Top View



Side View 1



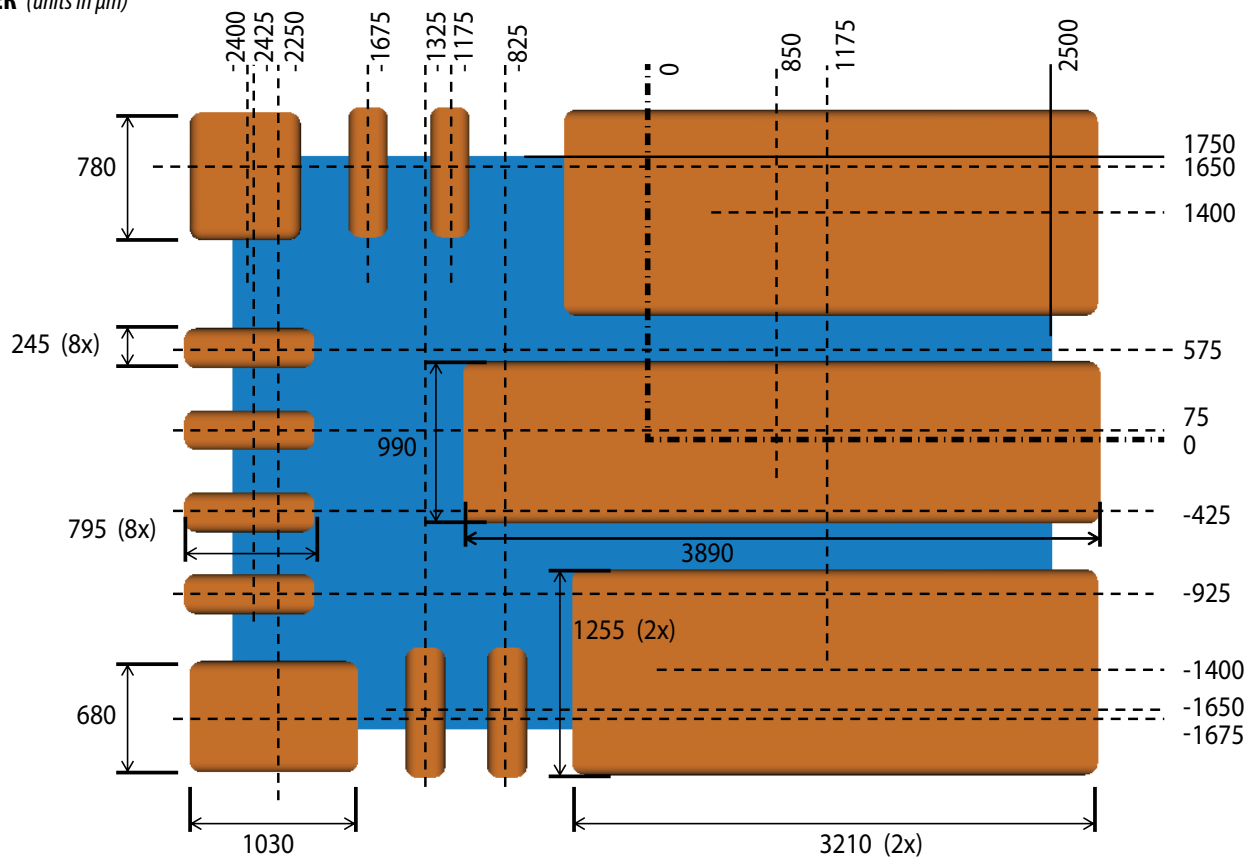
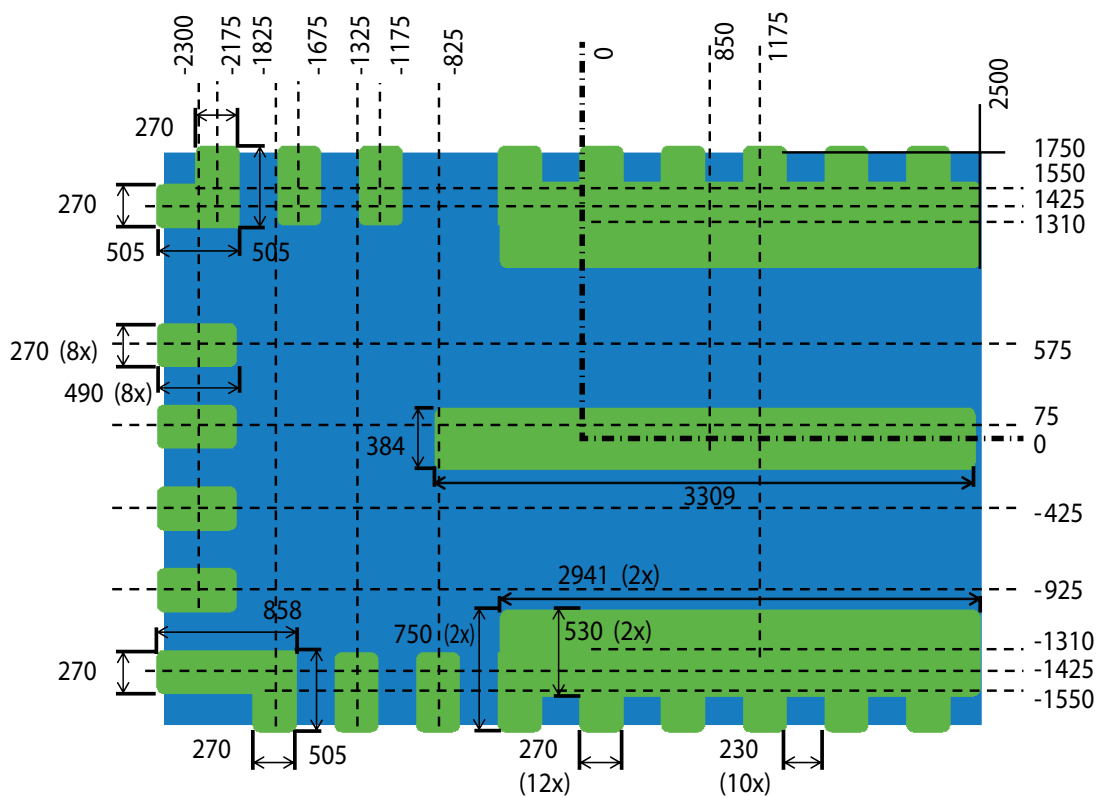
Bottom View

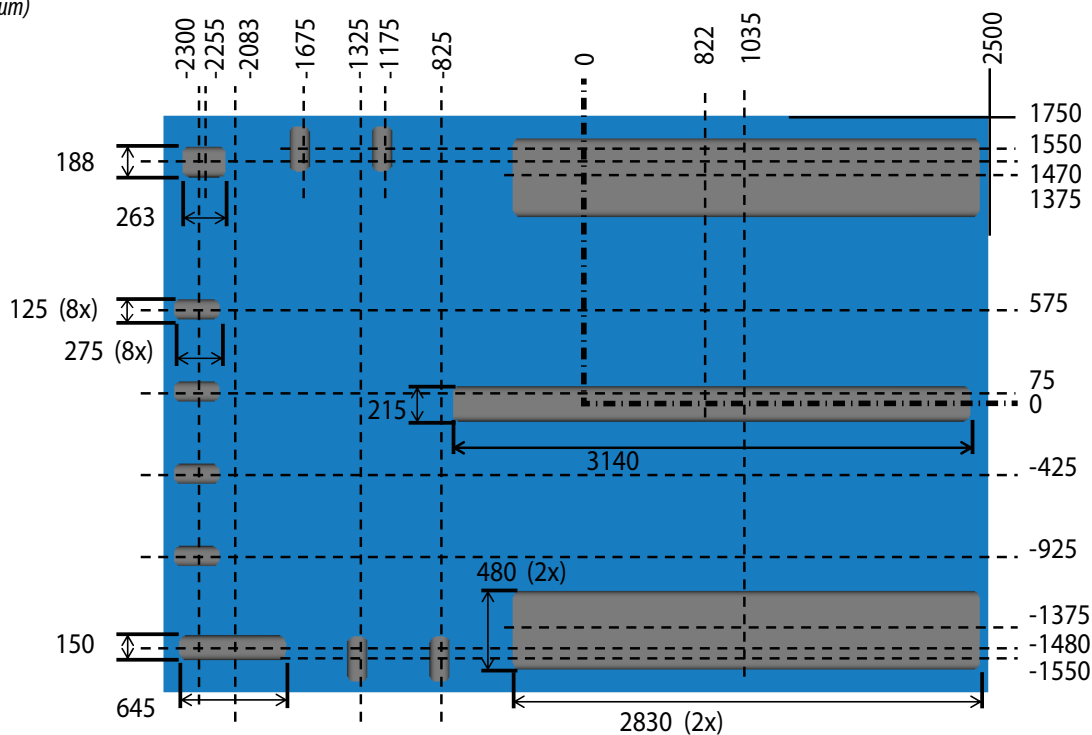
SYMBOL	Dimension (mm)			
	MIN	Nominal	MAX	Note
A	0.60	0.65	0.70	
A1	0.00	0.02	0.05	
A3		0.20 Ref		
b	0.20	0.25	0.30	6
b1	0.38	0.43	0.48	6
b2	0.49	0.54	0.59	
D		3.50 BSC		
E		5.00 BSC		
e		0.50 BSC		
K	0.55	0.60	0.65	
K1	0.12	0.17	0.22	
K2	0.775	0.825	0.875	
K3	0.15	0.20	0.25	

SYMBOL	Dimension (mm)			
	MIN	Nominal	MAX	Note
L	0.30	0.40	0.50	
L1	2.85	2.95	3.05	
L2	3.25	3.35	3.45	
aaa		0.05		
bbb		0.10		
ccc		0.10		
ddd		0.05		
eee		0.08		
N		13		3
ND		6		5
NE		4		5
Notes		1, 2		

## Notes:

1. Dimensioning and tolerancing conform to ASME Y14.5-2009
2. All dimensions are in millimeters
3. **N** is the total number of terminals
4. Dimension **b** applies to the metallized terminal. If the terminal has a radius on the other end of it, dimension **b** should not be measured in that radius area.
5. **ND** and **NE** refer to the number of terminals on each **D** and **E** side respectively.
6. Dimension **b** applies to the metallized terminal and is measured between 0.15 mm and 0.30 mm from the terminal tip. If the terminal has a radius on the other end of it, dimension **b** should not be measured in that radius area.
7. Coplanarity applies to the terminals and all the other bottom surface metallization.

**COPPER** (units in  $\mu\text{m}$ )**SOLDER MASK** (units in  $\mu\text{m}$ )

**PASTE** (units in  $\mu\text{m}$ )**PACKAGE** (units in  $\mu\text{m}$ )